



ASE GROUP



日月光集團

2016 第四季法人說明會

吳田玉
集團營運長

2017年1月26日

免責聲明



This presentation contains "forward-looking statements" within the meaning of Section 27A of the United States Securities Act of 1933, as amended, and Section 21E of the United States Securities Exchange Act of 1934, as amended, including statements regarding our future results of operations and business prospects. Although these forward-looking statements, which may include statements regarding our future results of operations, financial condition or business prospects, are based on our own information and information from other sources we believe to be reliable, you should not place undue reliance on these forward-looking statements, which apply only as of the date of this press release. The words "anticipate," "believe," "estimate," "expect," "intend," "plan" and similar expressions, as they relate to us, are intended to identify these forward-looking statements in this presentation. Our actual results of operations, financial condition or business prospects may differ materially from those expressed or implied in these forward-looking statements for a variety of reasons, including risks associated with cyclicity and market conditions in the semiconductor or electronic industry; changes in our regulatory environment, including our ability to comply with new or stricter environmental regulations and to resolve environmental liabilities; demand for the outsourced semiconductor packaging, testing and electronic manufacturing services we offer and for such outsourced services generally; the highly competitive semiconductor or manufacturing industry we are involved in; our ability to introduce new technologies in order to remain competitive; international business activities; our business strategy; our future expansion plans and capital expenditures; the uncertainties as to whether we can complete the acquisition of 100% of SPIL shares not otherwise owned by ASE; the strained relationship between the Republic of China and the People's Republic of China; general economic and political conditions; the recent global economic crisis; possible disruptions in commercial activities caused by natural or human-induced disasters; fluctuations in foreign currency exchange rates; and other factors. For a discussion of these risks and other factors, please see the documents we file from time to time with the Securities and Exchange Commission, including our 2015 Annual Report on Form 20-F filed on April 29, 2016.



日月光及矽品共同轉換股份協議最新消息



- 審議時程最新消息
 - 台灣:台灣公平交易委員會已核准通過日月光與矽品結合案
 - 中國:中華人民共和國商務部於2016年12月14日正式立案，第二階段審查進行中
 - 美國:於2017年1月17日，日月光與矽品各已依美國聯邦貿易委員會的要求回覆相關文件，並持續配合聯邦貿易委員會的調查
- 此交易預計於2017年完成，時程上的細節仍有待日月光及矽品股東會及相關審查機關通過後確立。
- 日月光將持續積極配合相關主管機關的審查。



日月光2016 營運概況

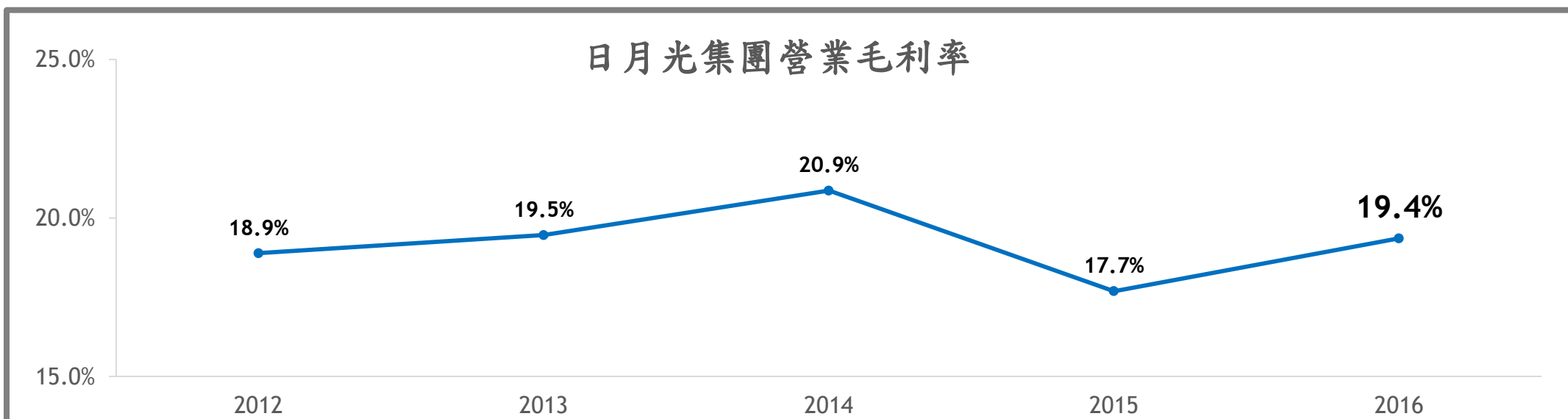
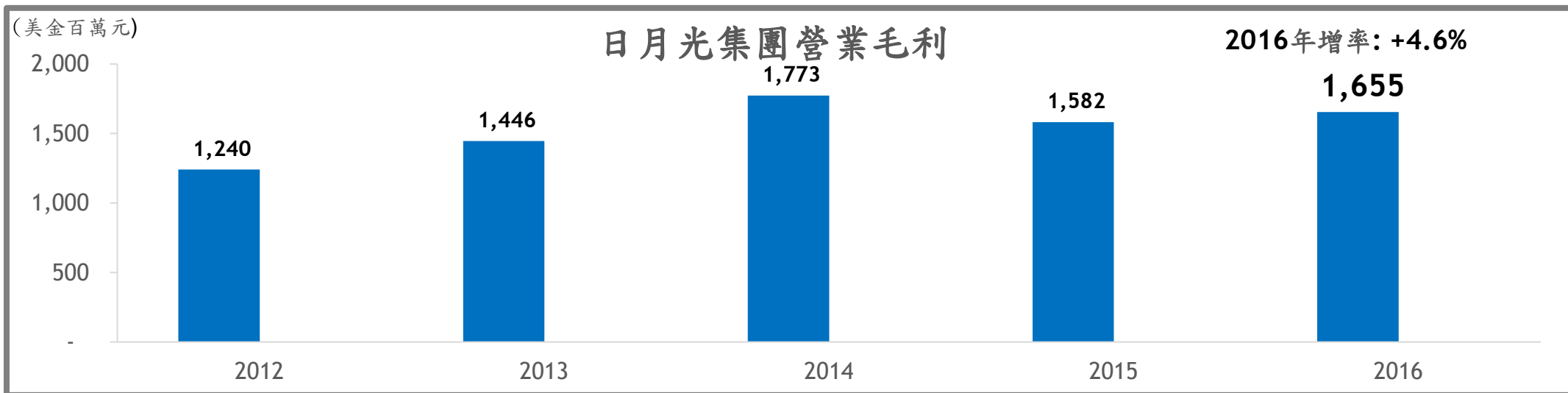


- 半導體封測營收年成長率達3.9%，為半導體產業成長率的兩倍
 - 成長主要動能來自 (1) 半導體封裝服務外包趨勢增加, (2) 日月光生產能力改進
 - 整體生意成長
 - 覆晶封裝, 凸塊及晶圓級封裝強勁新產品研發 - 營收年成長達13.7%
- 電子代工服務毛利率由2015年7.5%成長至2016年9.8%, 帶動日月光集團毛利增加
- 拓展技術發展
 - 扇外型封裝、銅柱凸塊封裝、內埋基板等等
- 企業社會責任

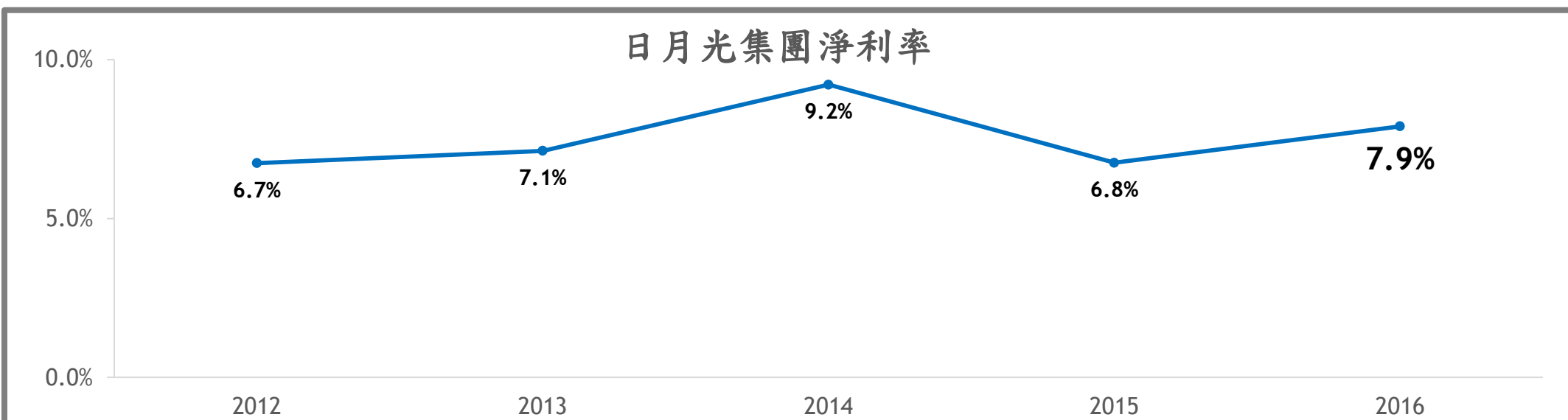
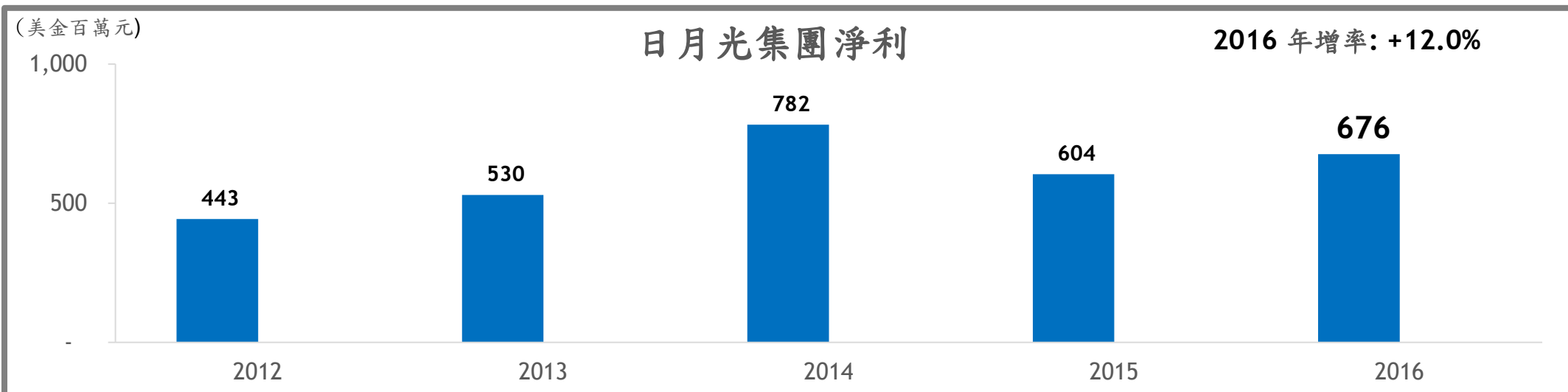
註: 所有財務結果係依照新台幣計算



日月光集團2016獲利及獲利率回升



日月光集團2016獲利及獲利率回升



2016日月光集團企業社會責任成就

日月光集團榮獲**2016 亞洲企業社會責任獎**。藉由日月光30 環保基金，做好台灣環境保育工作並善盡企業之社會責任。



日月光集團為台灣及半導體委外封測產業唯一榮獲 CDP 碳揭露計畫之**2016 氣候變遷年度評鑑A級**評價之企業。



MEMBER OF
Dow Jones Sustainability Indices
In Collaboration with RobecoSAM

榮獲產業領導者殊榮，首次獲得半導體及半導體設備產業組之產業領導者殊榮及榮獲道瓊永續世界指數成分股殊榮 (*Dow Jones Sustainability World index)。

*全球企業永續評比指標，追蹤大型企業在經濟、環境與社會面向上的績效表現。



日月光集團在2016由台灣永續能源研究基金會舉辦的台灣企業永續獎項活動中，榮獲**前五名企業永續報告獎**，**氣候領導獎**以及**供應鏈永續領導獎**。

綠建築認證標章

日月光集團於2016年底，共有十一棟建築獲得**台灣EEWH認證**以及**六項美國LEED認證**，包括三棟建築為白金等級。



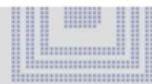
2017 業績展望及重點

- 進入2017年, 市場狀況應持續改善
- 預期今年年營收成長, 同時資本支出應比2016年水準高
- 著重於獲利及技術改善
- 執行擴展覆晶封裝, 凸塊及晶圓級封裝生意, 包含扇外型封裝
- 發展系統級封裝及內埋基板技術
- 完結矽品交易



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日月光半導體 2016第四季法人說明會

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Safe Harbor Notice



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合併綜合損益表

與上一季比較

(未經會計師查核)



(新台幣百萬元)	Q4 / 2016	%	Q3 / 2016	%	季變化
營業收入淨額:					
封裝	33,620	43.6%	33,449	46.0%	1%
測試	7,303	9.5%	7,231	9.9%	1%
材料直接銷售	806	1.0%	805	1.1%	0%
電子代工服務	34,627	44.9%	31,174	42.8%	11%
其它	772	1.0%	125	0.2%	518%
營業收入淨額合計	77,128	100.0%	72,784	100.0%	6%
營業毛利	15,377	19.9%	14,113	19.4%	9%
營業淨利 (淨損)	8,129	10.5%	7,438	10.2%	9%
稅前淨利 (淨損)	9,680	12.6%	6,875	9.4%	41%
所得稅利益 (費用)	(1,274)	-1.7%	(976)	-1.3%	
非控制權益	(430)	-0.6%	(393)	-0.5%	
歸屬於本公司業主之淨利	7,976	10.3%	5,506	7.6%	45%
基本每股盈餘 (新台幣元)	1.04		0.72		44%
稀釋每股盈餘 (新台幣元)	0.86		0.64		34%
EBITDA	17,449	22.6%	14,701	20.2%	19%



合併綜合損益表

與去年同期比較

(未經會計師查核)



(新台幣百萬元)	Q4 / 2016	%	Q4 / 2015	%	年變化
營業收入淨額:					
封裝	33,620	43.6%	29,093	38.5%	16%
測試	7,303	9.5%	6,355	8.4%	15%
材料直接銷售	806	1.0%	798	1.1%	1%
電子代工服務	34,627	44.9%	39,301	52.0%	-12%
其它	772	1.0%	1	0.0%	
營業收入淨額合計	77,128	100.0%	75,548	100.0%	2%
營業毛利	15,377	19.9%	13,269	17.6%	16%
營業淨利 (淨損)	8,129	10.5%	6,801	9.0%	20%
稅前淨利 (淨損)	9,680	12.6%	6,290	8.3%	54%
所得稅利益 (費用)	(1,274)	-1.7%	(1,259)	-1.7%	
非控制權益	(430)	-0.6%	(322)	-0.4%	
歸屬於本公司業主之淨利	7,976	10.3%	4,708	6.2%	69%
基本每股盈餘 (新台幣元)	1.04		0.62		68%
稀釋每股盈餘 (新台幣元)	0.86		0.60		43%
EBITDA	17,449	22.6%	14,189	18.8%	23%



合併綜合損益表

與去年全年比較

(未經會計師查核)



(新台幣百萬元)	FY / 2016	%	FY / 2015	%	年變化
營業收入淨額:					
封裝	125,283	45.6%	116,607	41.2%	7%
測試	27,032	9.8%	25,192	8.9%	7%
材料直接銷售	3,262	1.2%	3,260	1.2%	0%
電子代工服務	115,395	42.0%	138,242	48.8%	-17%
其它	3,912	1.4%	1	0.0%	
營業收入淨額合計	274,884	100.0%	283,302	100.0%	-3%
營業毛利	53,194	19.4%	50,135	17.7%	6%
營業淨利 (淨損)	26,704	9.7%	24,884	8.8%	7%
稅前淨利 (淨損)	28,052	10.2%	25,006	8.8%	12%
所得稅利益 (費用)	(5,091)	-1.9%	(4,839)	-1.7%	
非控制權益	(1,269)	-0.5%	(970)	-0.3%	
歸屬於本公司業主之淨利	21,692	7.9%	19,197	6.8%	13%
基本每股盈餘 (新台幣元)	2.83		2.51		13%
稀釋每股盈餘 (新台幣元)	2.35		2.41		-2%
EBITDA	59,356	21.6%	56,931	20.1%	4%



綜合損益表 – 半導體封裝測試

與上一季比較

(未經會計師查核)



(新台幣百萬元)	Q4 / 2016	%	Q3 / 2016	%	季變化
營業收入淨額:					
封裝	35,242	81.1%	34,832	81.0%	1%
測試	7,303	16.8%	7,232	16.8%	1%
材料直接銷售	898	2.1%	920	2.1%	-2%
其它	20	0.0%	22	0.1%	-9%
營業收入淨額合計	43,463	100.0%	43,006	100.0%	1%
營業毛利	11,647	26.8%	10,969	25.5%	6%
營業淨利 (淨損)	6,372	14.7%	6,193	14.4%	3%
稅前淨利 (淨損)	9,058	20.8%	6,319	14.7%	43%
所得稅利益 (費用)	(967)	-2.2%	(719)	-1.7%	
非控制權益	(115)	-0.3%	(94)	-0.2%	
歸屬於本公司業主之淨利	7,976	18.4%	5,506	12.8%	45%
EBITDA	14,969	34.4%	12,635	29.4%	18%



綜合損益表 – 半導體封裝測試

與去年同期比較

(未經會計師查核)



(新台幣百萬元)	Q4 / 2016	%	Q4 / 2015	%	年變化
營業收入淨額:					
封裝	35,242	81.1%	31,121	81.0%	13%
測試	7,303	16.8%	6,356	16.5%	15%
材料直接銷售	898	2.1%	910	2.4%	-1%
其它	20	0.0%	19	0.0%	5%
營業收入淨額合計	43,463	100.0%	38,406	100.0%	13%
營業毛利	11,647	26.8%	9,978	26.0%	17%
營業淨利 (淨損)	6,372	14.7%	5,313	13.8%	20%
稅前淨利 (淨損)	9,058	20.8%	5,858	15.3%	55%
所得稅利益 (費用)	(967)	-2.2%	(1,099)	-2.9%	
非控制權益	(115)	-0.3%	(51)	-0.1%	
歸屬於本公司業主之淨利	7,976	18.4%	4,708	12.3%	69%
EBITDA	14,969	34.4%	12,005	31.3%	25%



綜合損益表 – 半導體封裝測試

與去年全年比較

(未經會計師查核)

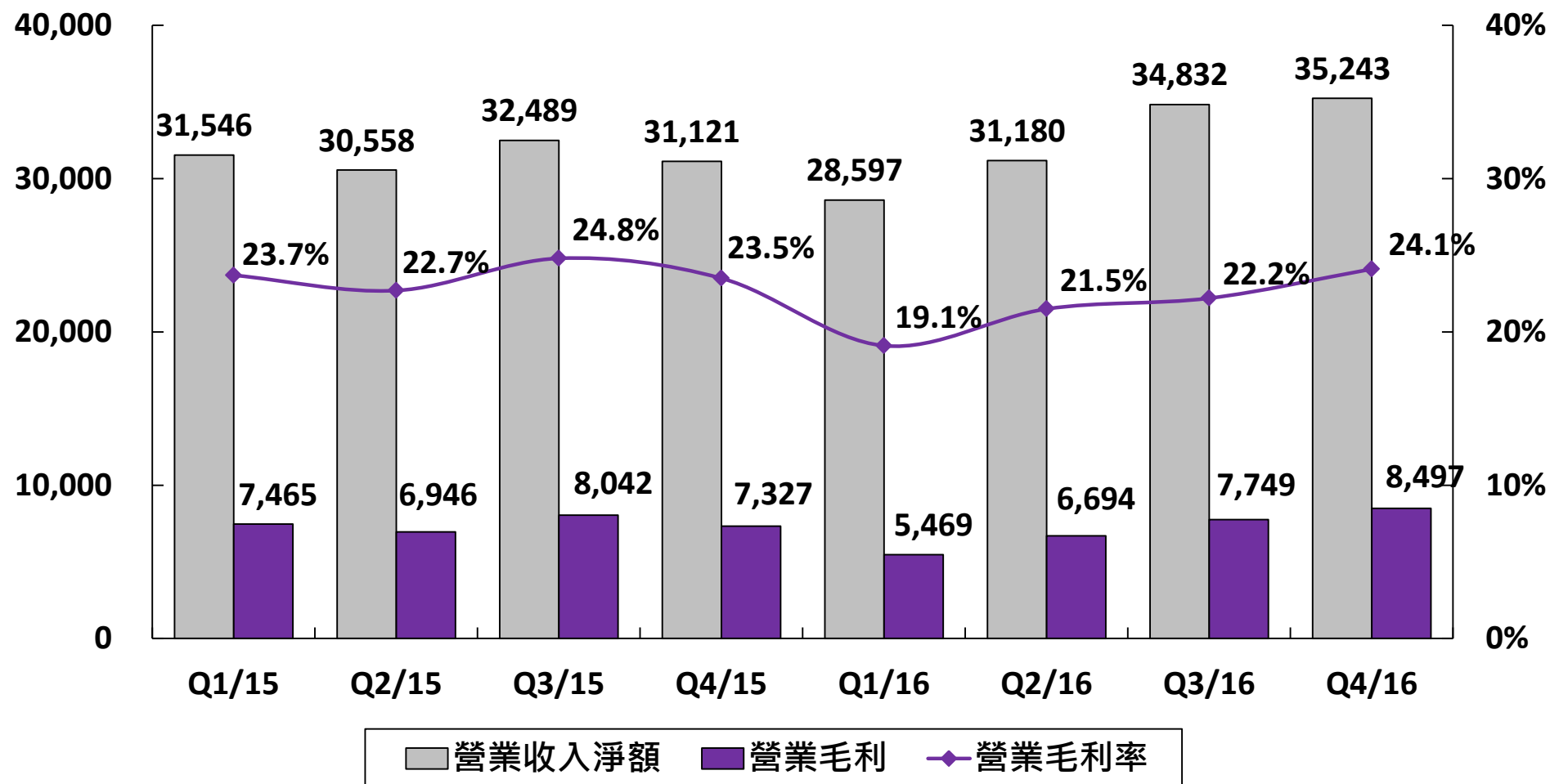


(新台幣百萬元)	FY / 2016	%	FY / 2015	%	年變化
營業收入淨額:					
封裝	129,851	80.9%	125,714	81.3%	3%
測試	27,032	16.8%	25,192	16.3%	7%
材料直接銷售	3,550	2.2%	3,564	2.3%	0%
其它	83	0.1%	74	0.0%	12%
營業收入淨額合計	160,516	100.0%	154,544	100.0%	4%
營業毛利	40,009	24.9%	40,128	26.0%	0%
營業淨利 (淨損)	20,744	12.9%	21,604	14.0%	-4%
稅前淨利 (淨損)	25,492	15.9%	23,750	15.4%	7%
所得稅利益 (費用)	(3,481)	-2.2%	(4,361)	-2.8%	
非控制權益	(319)	-0.2%	(192)	-0.1%	
歸屬於本公司業主之淨利	21,692	13.5%	19,197	12.4%	13%
EBITDA	50,391	31.4%	50,459	32.7%	0%



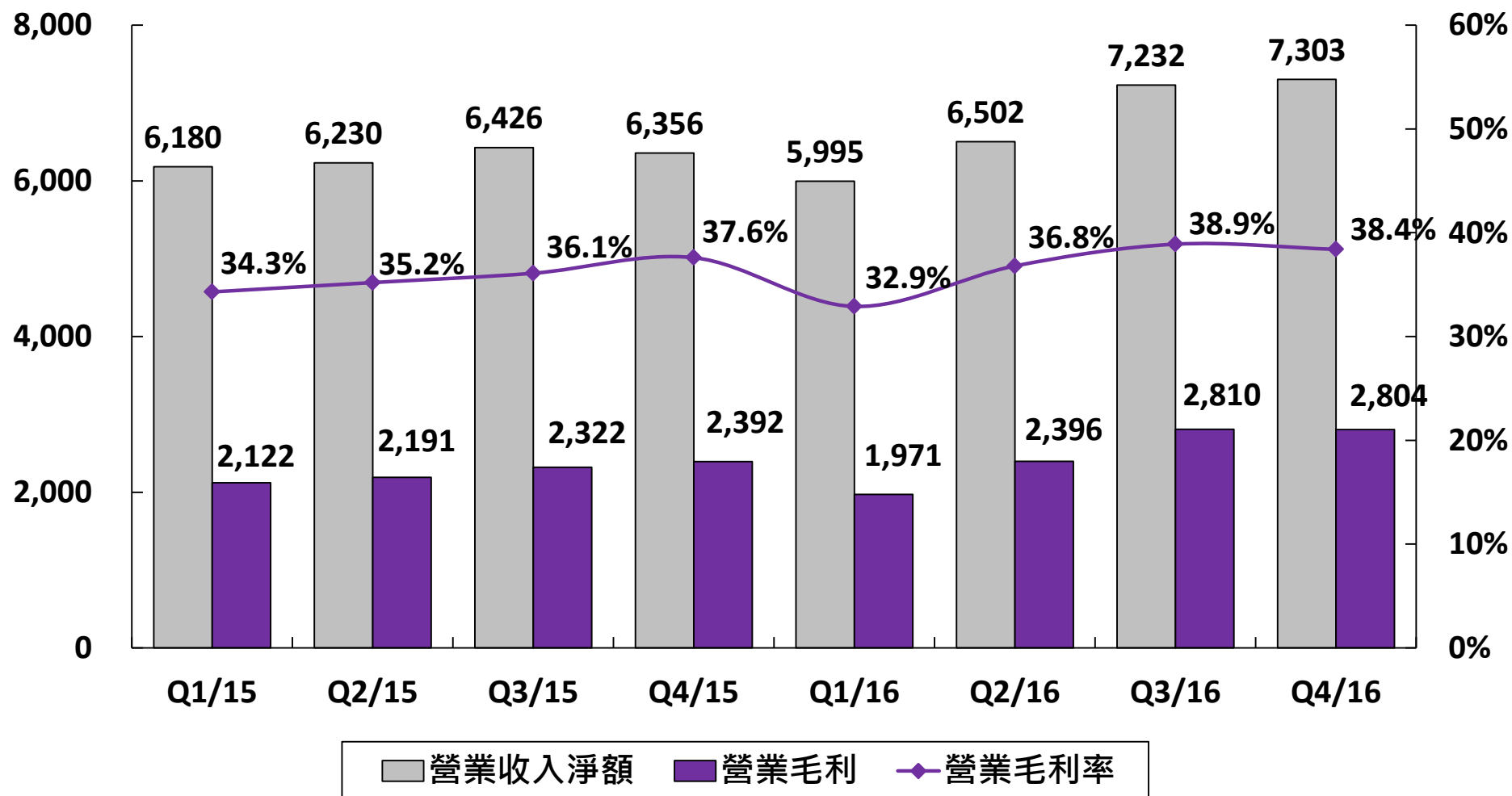
封裝業務

新台幣百萬元



測試業務

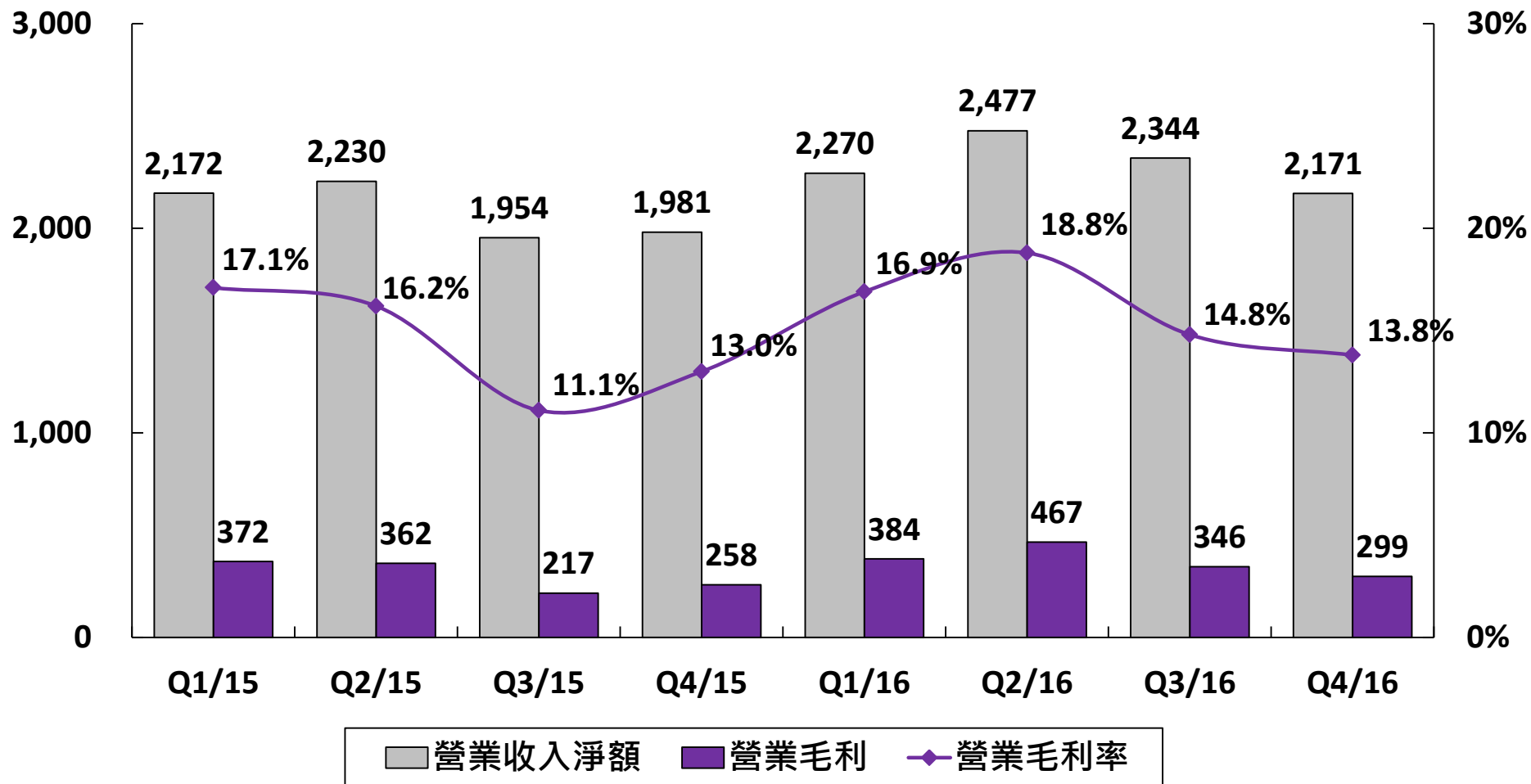
新台幣百萬元



材料業務

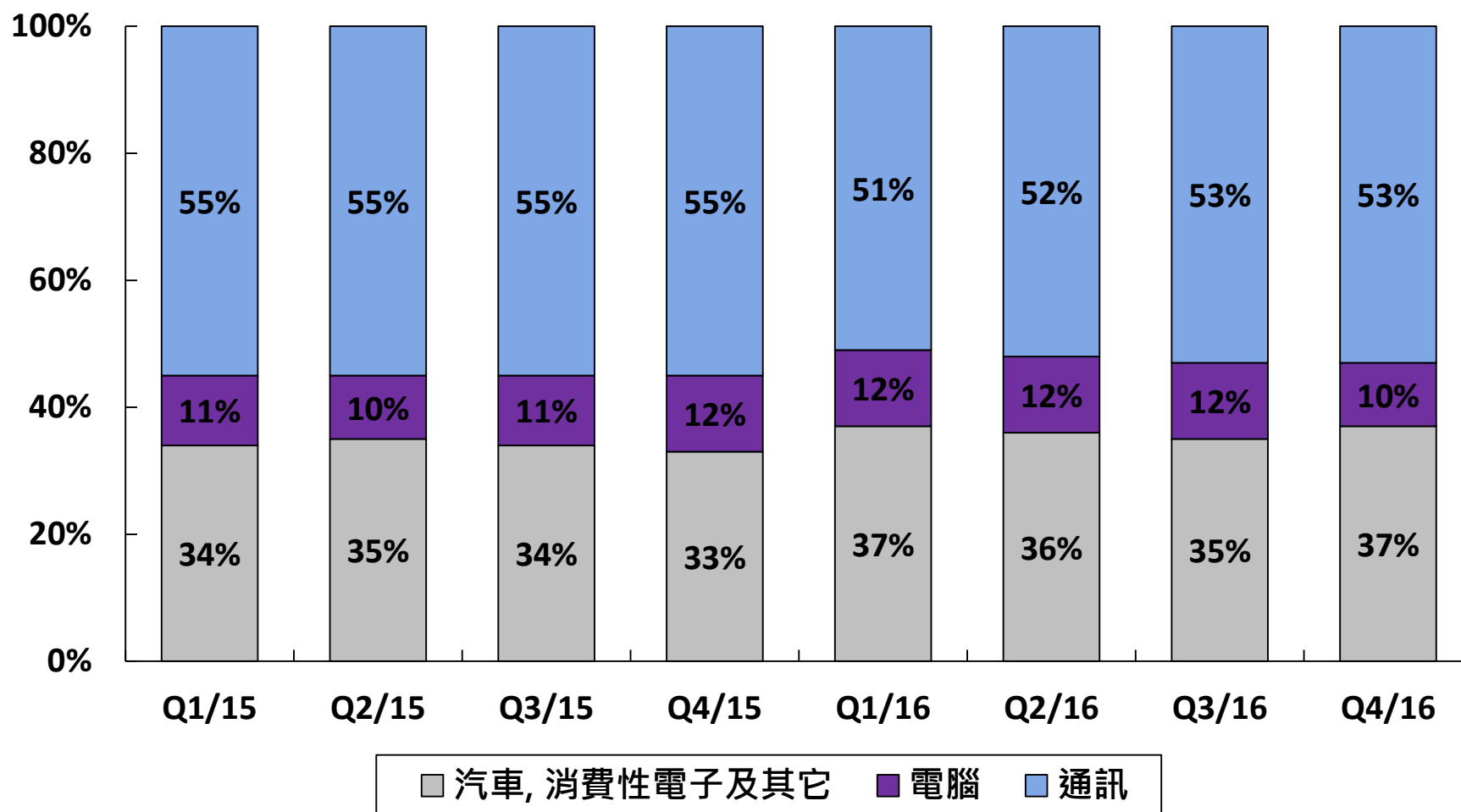


新台幣百萬元



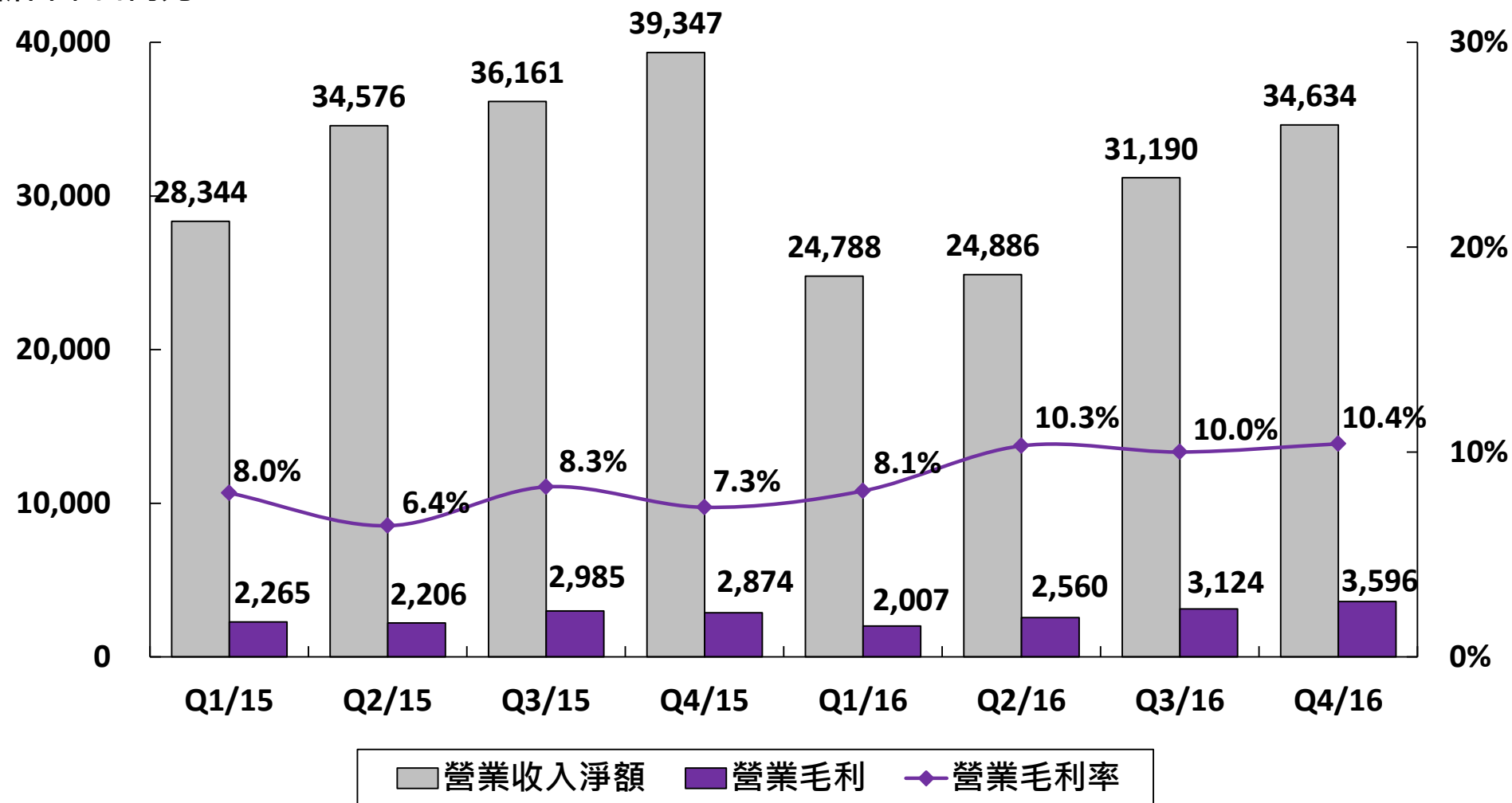
半導體封測營收

產品應用別佔比



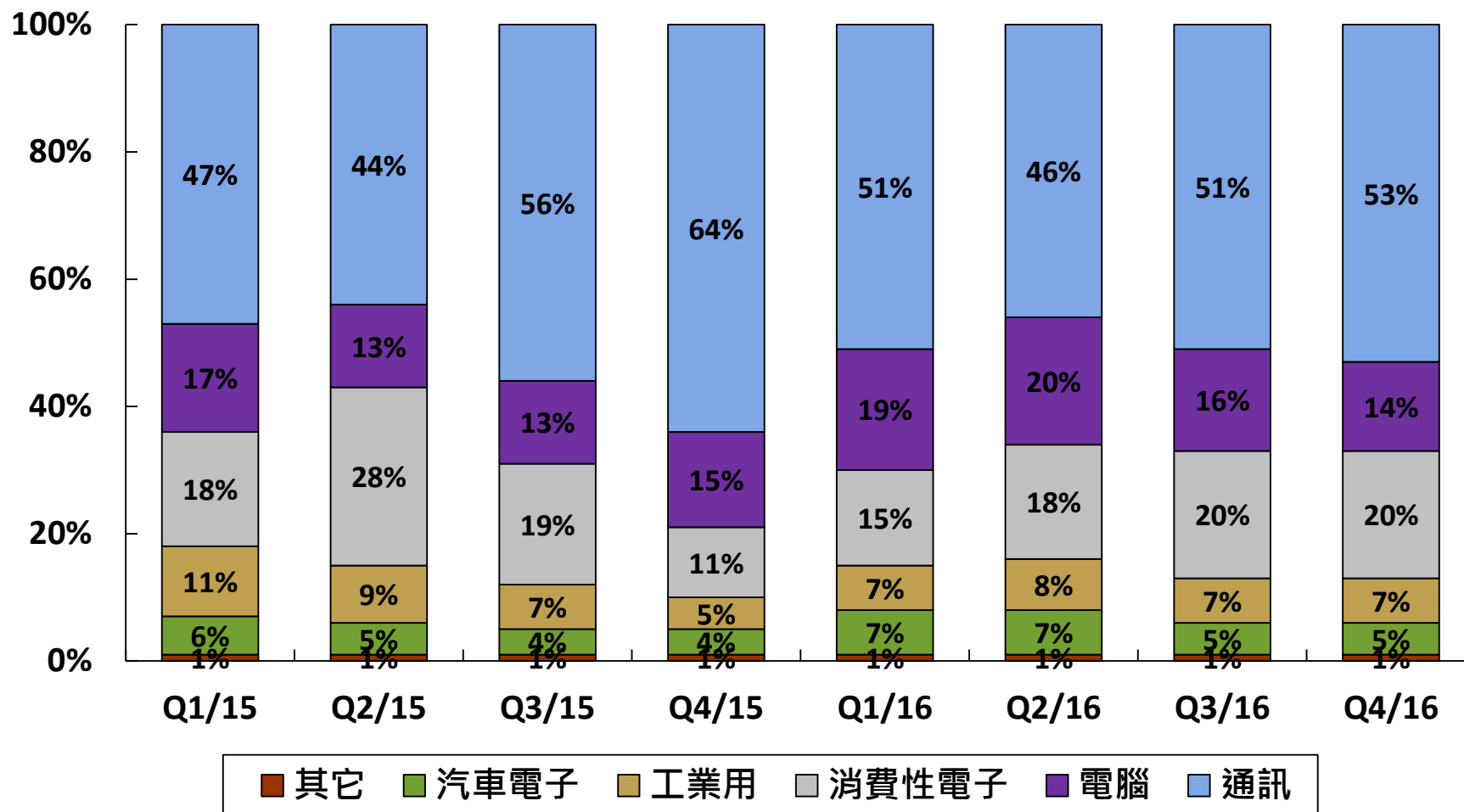
電子代工服務業務

新台幣百萬元



電子代工服務業務

產品應用別



重要資產負債表項目及財務指標

(未經會計師查核)



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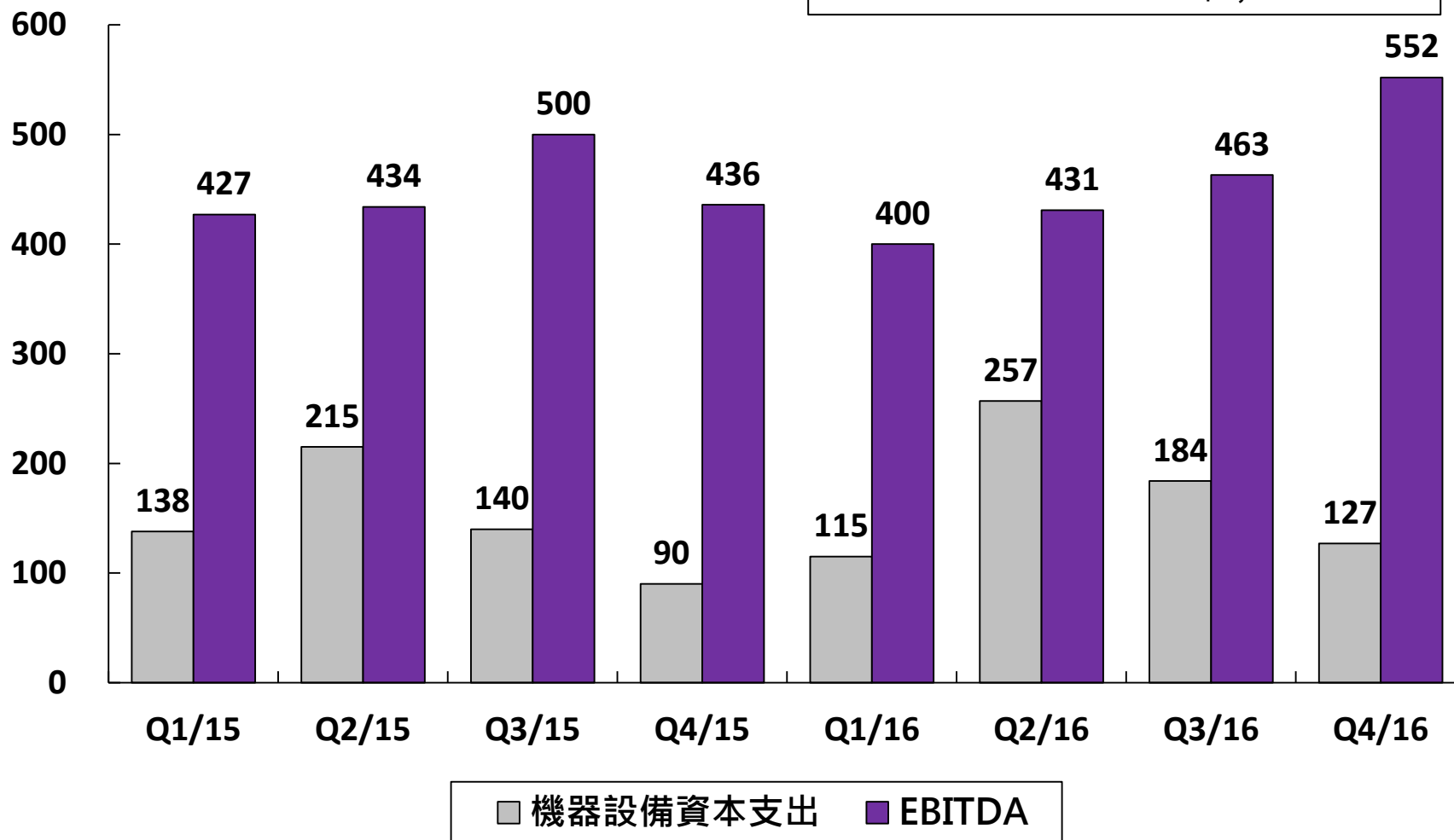
(新台幣百萬元)	2016年12月31日	2016年9月30日	季變化
現金及約當現金	38,392	37,661	1.9%
金融資產 - 流動	3,895	1,931	101.7%
金融資產 - 非流動及採用權益法之投資	52,174	51,975	0.4%
不動產、廠房及設備	143,880	145,209	-0.9%
資產總計	357,943	360,628	-0.7%
短期借款及應付短期票券	20,955	33,007	-36.5%
一年內到期之應付公司債	9,658	9,385	2.9%
一年內到期之長期借款及應付租賃款	6,683	6,384	4.7%
應付公司債	27,342	26,872	1.7%
長期借款及應付租賃款	47,013	44,255	6.2%
權益總計 (含非控制權益)	169,570	161,218	5.2%
當季 EBITDA	17,449	14,701	18.7%
流動比率	1.37	1.21	
負債權益比率	0.41	0.50	



機器設備資本支出及EBITDA

美金百萬元

2016年全年資本支出: US\$683 百萬元
2016年全年EBITDA: US\$1,846 百萬元



2017年第一季業績展望

根據對當前業務狀況的評估及匯率的假設，日月光公司2017年第一季的業績展望如下：

- 半導體封測事業第一季生意量將接近去年第二季水準
- 半導體封測事業第一季毛利率將與去年上半年水準相仿
- 電子代工服務第一季生意量與毛利率皆將與去年季平均相仿



Thank You

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